

ABSTRACT

[Problem] Provided is a thermally and electrically conductive adhesive composition used as a die-bonding material which shows high heat dissipation performance and stable electric conductivity as well as high adhesion force.

[Solution] Provided is a thermally and electrically conductive adhesive composition, comprising: (A) an electrically conductive filler; (B) an epoxy resin; (C) a curing agent, and (D) an organic solvent, in which the electrically conductive filler (A) is a submicron fine silver powder, and the content of the electrically conductive filler (A) is such that (A) / (B) is 96.0 / 4.0 to 99.5 / 0.5 in the mass ratio to the content of the epoxy resin (B); and the epoxy resin (B) comprises at least a bisphenol-type epoxy resin and a novolac-type epoxy resin; and the curing agent (C) is diaminodiphenyl sulfone and/or a derivative thereof, and the content of the curing agent (C) is 0.4 to 2.4 molar equivalents in terms of equivalent of active hydrogen relative to 1 molar equivalent of epoxy groups in the epoxy resin (B).

[Selected Figure] None